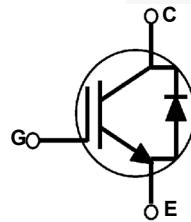
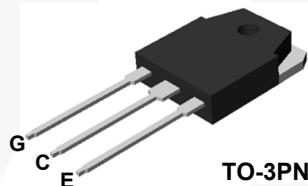


# FGA40T65SHDF

## 650 V, 40 A Field Stop Trench IGBT

### Features

- Maximum Junction Temperature :  $T_J = 175^\circ\text{C}$
- Positive Temperature Co-efficient for Easy Parallel Operating
- High Current Capability
- Low Saturation Voltage:  $V_{CE(\text{sat})} = 1.45 \text{ V (Typ.)} @ I_C = 40 \text{ A}$
- 100% of the Parts tested for  $I_{LM}(1)$
- High Input Impedance
- Fast Switching
- Tighten Parameter Distribution
- RoHS Compliant



### Absolute Maximum Ratings

$T_C = 25^\circ\text{C}$  unless otherwise noted

Symbol	Description	FGA40T65SHDF	Unit
$V_{CES}$	Collector to Emitter Voltage	650	V
$V_{GES}$	Gate to Emitter Voltage	$\pm 20$	V
	Transient Gate to Emitter Voltage	$\pm 30$	V
$I_C$	Collector Current @ $T_C = 25^\circ\text{C}$	80	A
	Collector Current @ $T_C = 100^\circ\text{C}$	40	A
$I_{LM}(1)$	Pulsed Collector Current @ $T_C = 25^\circ\text{C}$	120	A
$I_{CM}(2)$	Pulsed Collector Current	120	A
$I_F$	Diode Forward Current @ $T_C = 25^\circ\text{C}$	40	A
	Diode Forward Current @ $T_C = 100^\circ\text{C}$	20	A
$I_{FM}$	Pulsed Diode Maximum Forward Current	60	A
$P_D$	Maximum Power Dissipation @ $T_C = 25^\circ\text{C}$	268	W
	Maximum Power Dissipation @ $T_C = 100^\circ\text{C}$	134	W
$T_J$	Operating Junction Temperature	-55 to +175	$^\circ\text{C}$
$T_{stg}$	Storage Temperature Range	-55 to +175	$^\circ\text{C}$
$T_L$	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

#### Notes:

1.  $V_{CC} = 400 \text{ V}$ ,  $V_{GE} = 15 \text{ V}$ ,  $I_C = 120 \text{ A}$ ,  $R_G = 30 \Omega$ , Inductive Load
2. Repetitive rating: Pulse width limited by max. junction temperature

## Thermal Characteristics

Symbol	Parameter	FGA40T65SHDF	Unit
$R_{\thetaJC}$ (IGBT)	Thermal Resistance, Junction to Case, Max.	0.56	°C/W
$R_{\thetaJC}$ (Diode)	Thermal Resistance, Junction to Case, Max.	1.75	°C/W
$R_{\thetaJA}$	Thermal Resistance, Junction to Ambient, Max.	40	°C/W

## Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FGA40T65SHDF	FGA40T65SHDF	TO-3PN	Tube	-	-	30

## Electrical Characteristics of the IGBT $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
$BV_{CES}$	Collector to Emitter Breakdown Voltage	$V_{GE} = 0 \text{ V}$ , $I_C = 1 \text{ mA}$	650	-	-	V
$\Delta BV_{CES}/\Delta T_J$	Temperature Coefficient of Breakdown Voltage	$V_{GE} = 0 \text{ V}$ , $I_C = 1 \text{ mA}$	-	0.6	-	V/°C
$I_{CES}$	Collector Cut-Off Current	$V_{CE} = V_{CES}$ , $V_{GE} = 0 \text{ V}$	-	-	250	μA
$I_{GES}$	G-E Leakage Current	$V_{GE} = V_{GES}$ , $V_{CE} = 0 \text{ V}$	-	-	± 400	nA
<b>On Characteristics</b>						
$V_{GE(\text{th})}$	G-E Threshold Voltage	$I_C = 40 \text{ mA}$ , $V_{CE} = V_{GE}$	4.0	5.5	7.5	V
$V_{CE(\text{sat})}$	Collector to Emitter Saturation Voltage	$I_C = 40 \text{ A}$ , $V_{GE} = 15 \text{ V}$	-	1.45	1.81	V
		$I_C = 40 \text{ A}$ , $V_{GE} = 15 \text{ V}$ , $T_C = 175^\circ\text{C}$	-	1.8	-	V
<b>Dynamic Characteristics</b>						
$C_{ies}$	Input Capacitance	$V_{CE} = 30 \text{ V}$ , $V_{GE} = 0 \text{ V}$ , $f = 1 \text{ MHz}$	-	1982	-	pF
$C_{oes}$	Output Capacitance		-	70	-	pF
$C_{res}$	Reverse Transfer Capacitance		-	25	-	pF
<b>Switching Characteristics</b>						
$T_{d(on)}$	Turn-On Delay Time	$V_{CC} = 400 \text{ V}$ , $I_C = 40 \text{ A}$ , $R_G = 6 \Omega$ , $V_{GE} = 15 \text{ V}$ , Inductive Load, $T_C = 25^\circ\text{C}$	-	18	-	ns
$T_r$	Rise Time		-	27	-	ns
$T_{d(off)}$	Turn-Off Delay Time		-	64	-	ns
$T_f$	Fall Time		-	3	-	ns
$E_{on}$	Turn-On Switching Loss		-	1.22	-	mJ
$E_{off}$	Turn-Off Switching Loss		-	0.44	-	mJ
$E_{ts}$	Total Switching Loss		-	1.66	-	mJ
$T_{d(on)}$	Turn-On Delay Time		-	18	-	ns
$T_r$	Rise Time	$V_{CC} = 400 \text{ V}$ , $I_C = 40 \text{ A}$ , $R_G = 6 \Omega$ , $V_{GE} = 15 \text{ V}$ , Inductive Load, $T_C = 175^\circ\text{C}$	-	31	-	ns
$T_{d(off)}$	Turn-Off Delay Time		-	70	-	ns
$T_f$	Fall Time		-	56	-	ns
$E_{on}$	Turn-On Switching Loss		-	1.78	-	mJ
$E_{off}$	Turn-Off Switching Loss		-	0.78	-	mJ
$E_{ts}$	Total Switching Loss		-	2.56	-	mJ

## Electrical Characteristics of the IGBT (Continued)

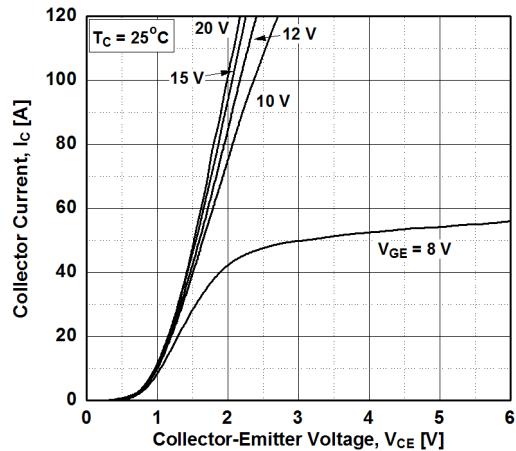
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$Q_g$	Total Gate Charge	$V_{CE} = 400$ V, $I_C = 40$ A, $V_{GE} = 15$ V	-	68	-	nC
$Q_{ge}$	Gate to Emitter Charge		-	12	-	nC
$Q_{gc}$	Gate to Collector Charge		-	25	-	nC

## Electrical Characteristics of the Diode $T_C = 25^\circ\text{C}$ unless otherwise noted

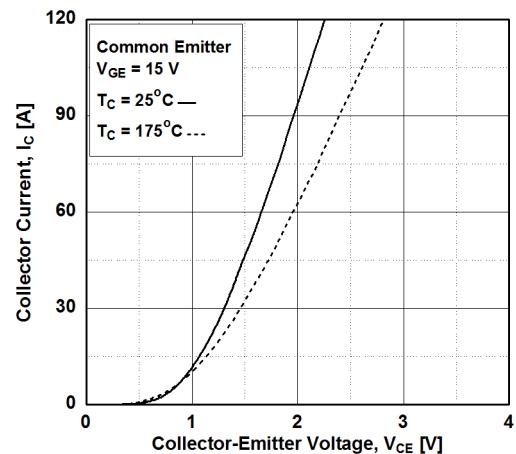
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{FM}$	Diode Forward Voltage	$I_F = 20$ A	$T_C = 25^\circ\text{C}$	-	1.5	1.95
			$T_C = 175^\circ\text{C}$	-	1.37	-
$E_{rec}$	Reverse Recovery Energy	$I_F = 20$ A, $dI_F/dt = 200$ A/ $\mu\text{s}$	$T_C = 175^\circ\text{C}$	-	153	-
			$T_C = 25^\circ\text{C}$	-	101	-
$T_{rr}$	Diode Reverse Recovery Time		$T_C = 175^\circ\text{C}$	-	238	-
			$T_C = 25^\circ\text{C}$	-	343	-
$Q_{rr}$	Diode Reverse Recovery Charge		$T_C = 175^\circ\text{C}$	-	1493	-
			$T_C = 25^\circ\text{C}$	-	-	nC

## Typical Performance Characteristics

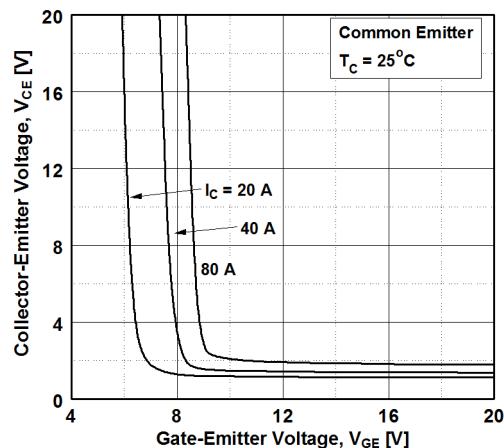
**Figure 1. Typical Output Characteristics**



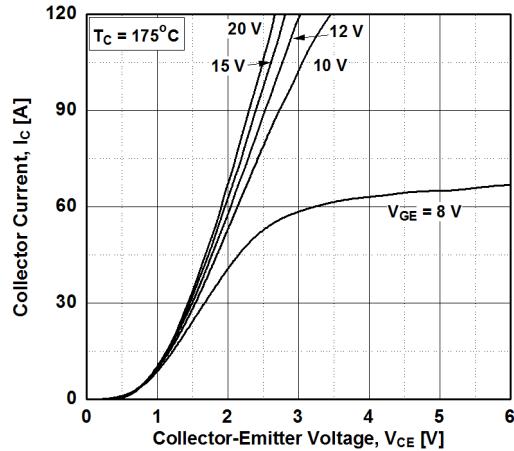
**Figure 3. Typical Saturation Voltage Characteristics**



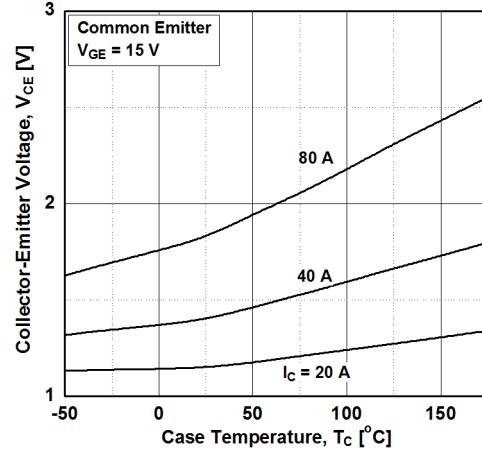
**Figure 5. Saturation Voltage vs. V<sub>GE</sub>**



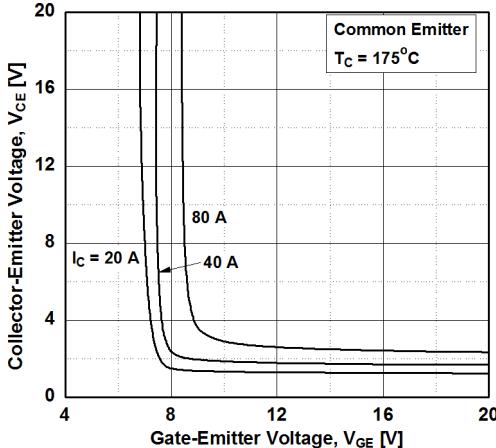
**Figure 2. Typical Output Characteristics**



**Figure 4. Saturation Voltage vs. Case Temperature at Variant Current Level**

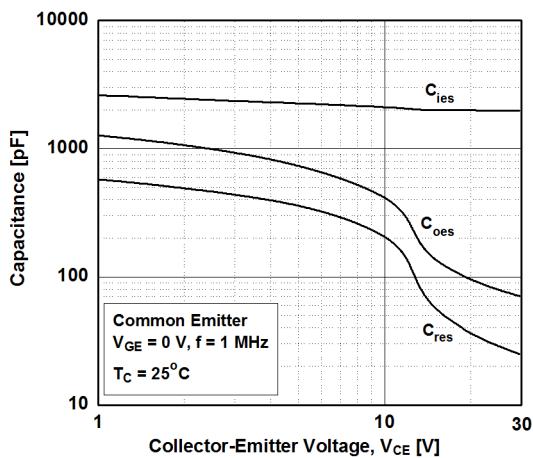


**Figure 6. Saturation Voltage vs. V<sub>GE</sub>**

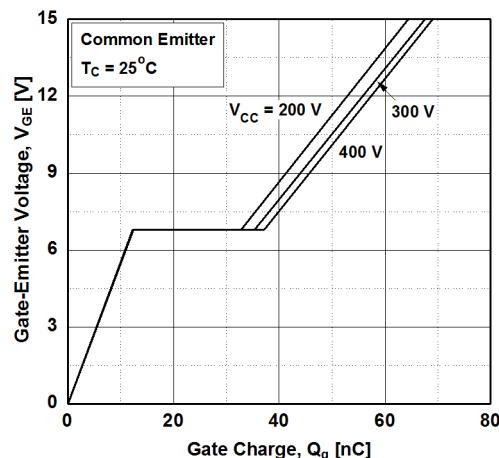


## Typical Performance Characteristics

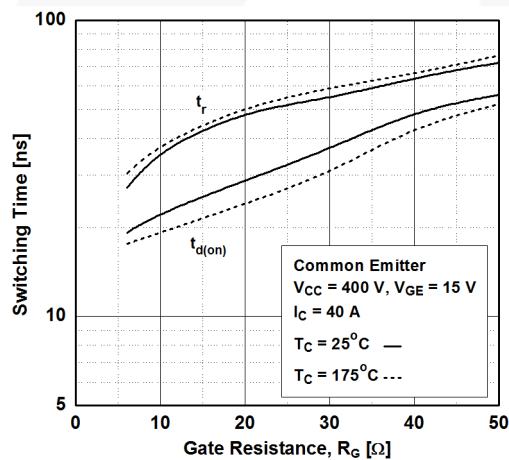
**Figure 7. Capacitance Characteristics**



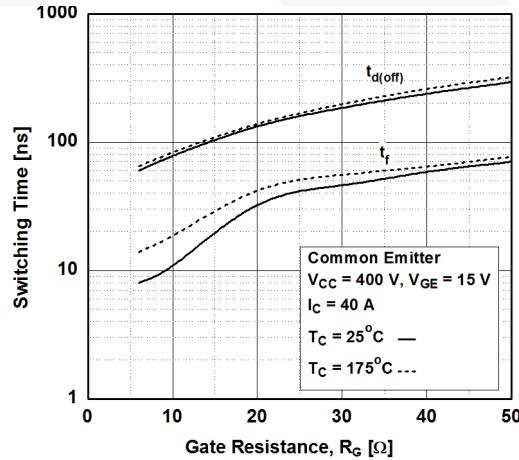
**Figure 8. Gate charge Characteristics**



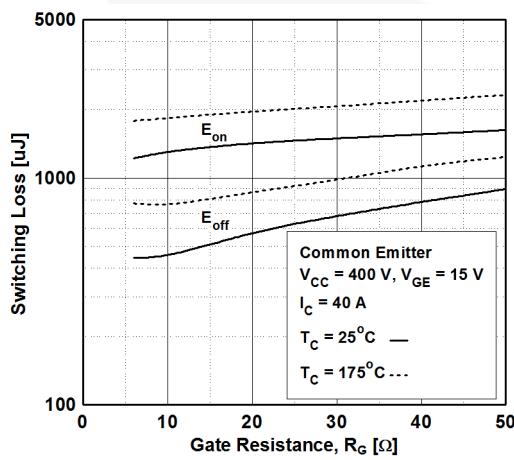
**Figure 9. Turn-on Characteristics vs. Gate Resistance**



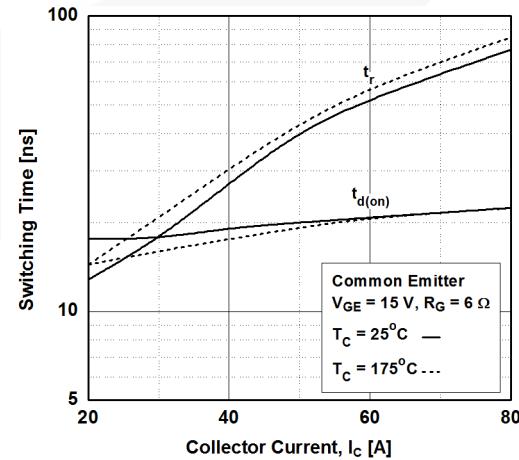
**Figure 10. Turn-off Characteristics vs. Gate Resistance**



**Figure 11. Switching Loss vs. Gate Resistance**



**Figure 12. Turn-on Characteristics vs. Collector Current**



## Typical Performance Characteristics

Figure 13. Turn-off Characteristics vs. Collector Current

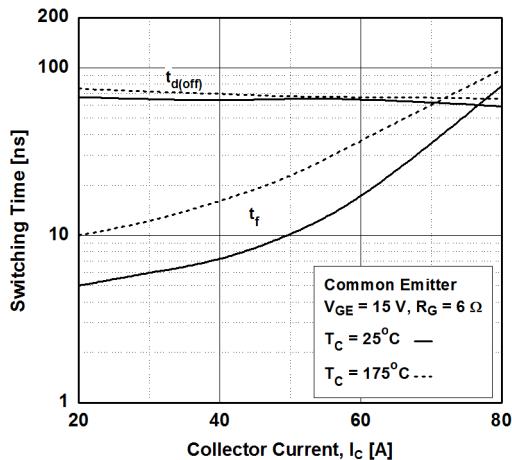


Figure 15. Load Current Vs. Frequency

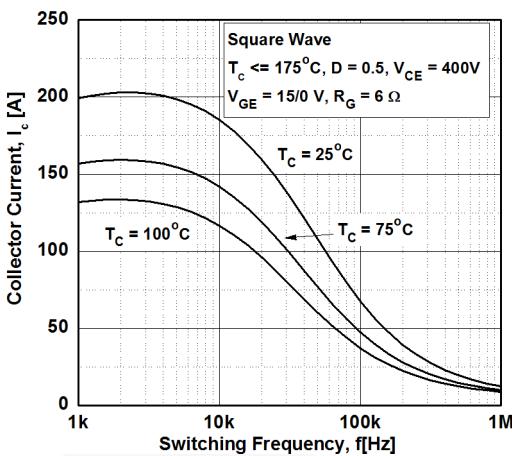


Figure 17. Forward Characteristics

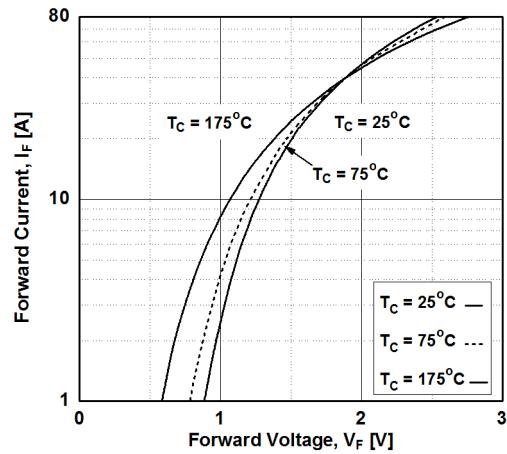


Figure 14. Switching Loss vs. Collector Current

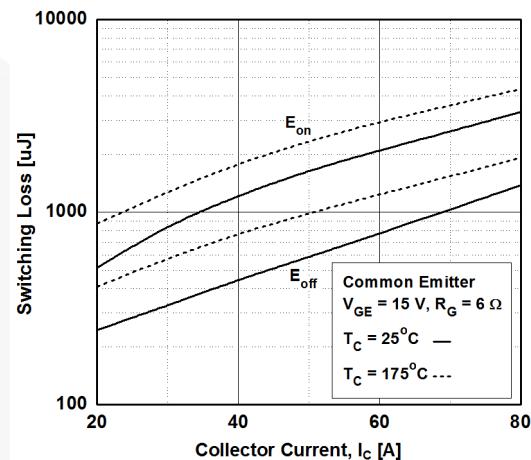


Figure 16. SOA Characteristics

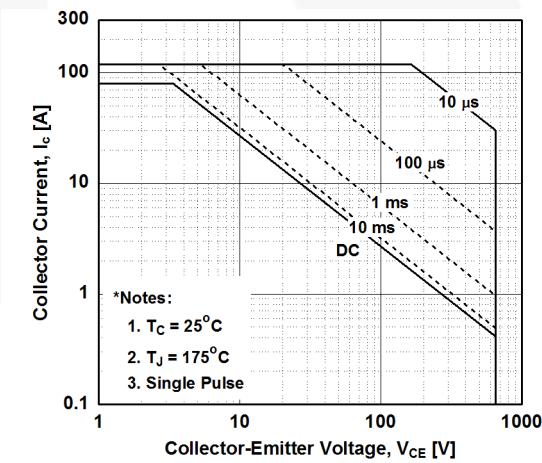
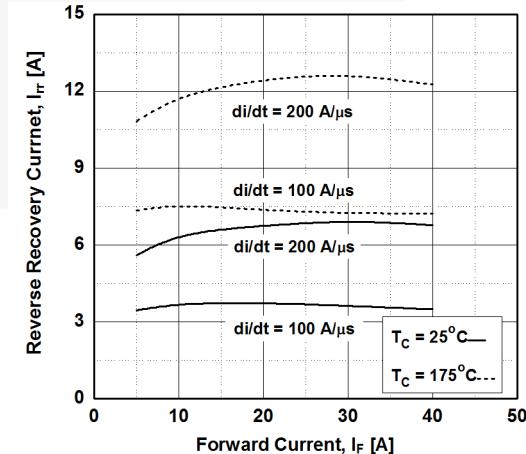


Figure 18. Reverse Recovery Current



## Typical Performance Characteristics

Figure 19. Reverse Recovery Time

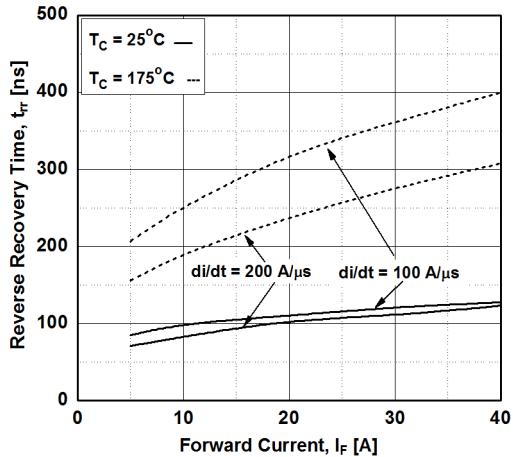


Figure 20. Stored Charge

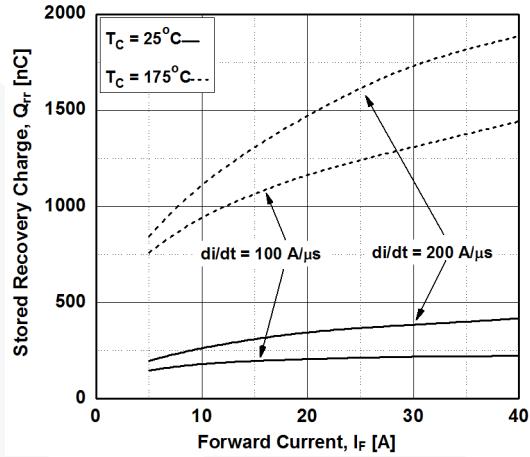


Figure 21. Transient Thermal Impedance of IGBT

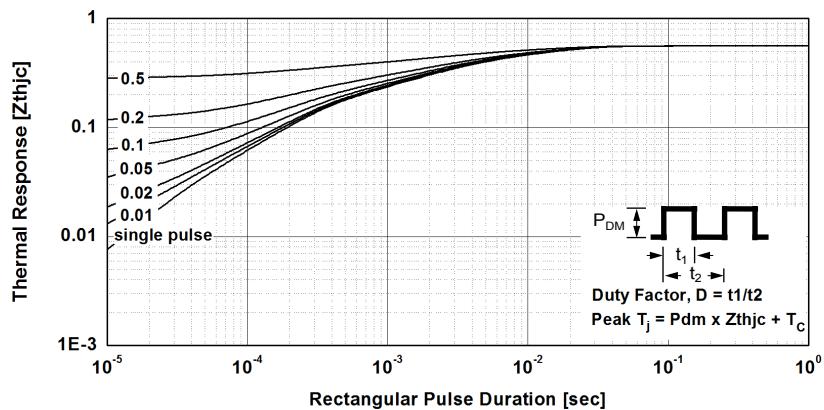
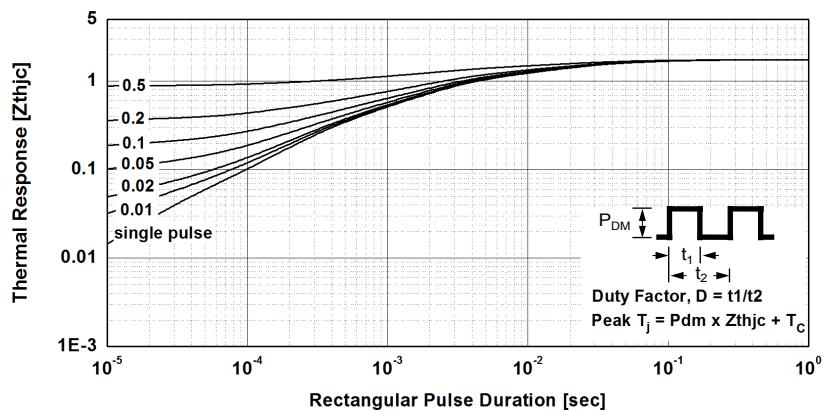
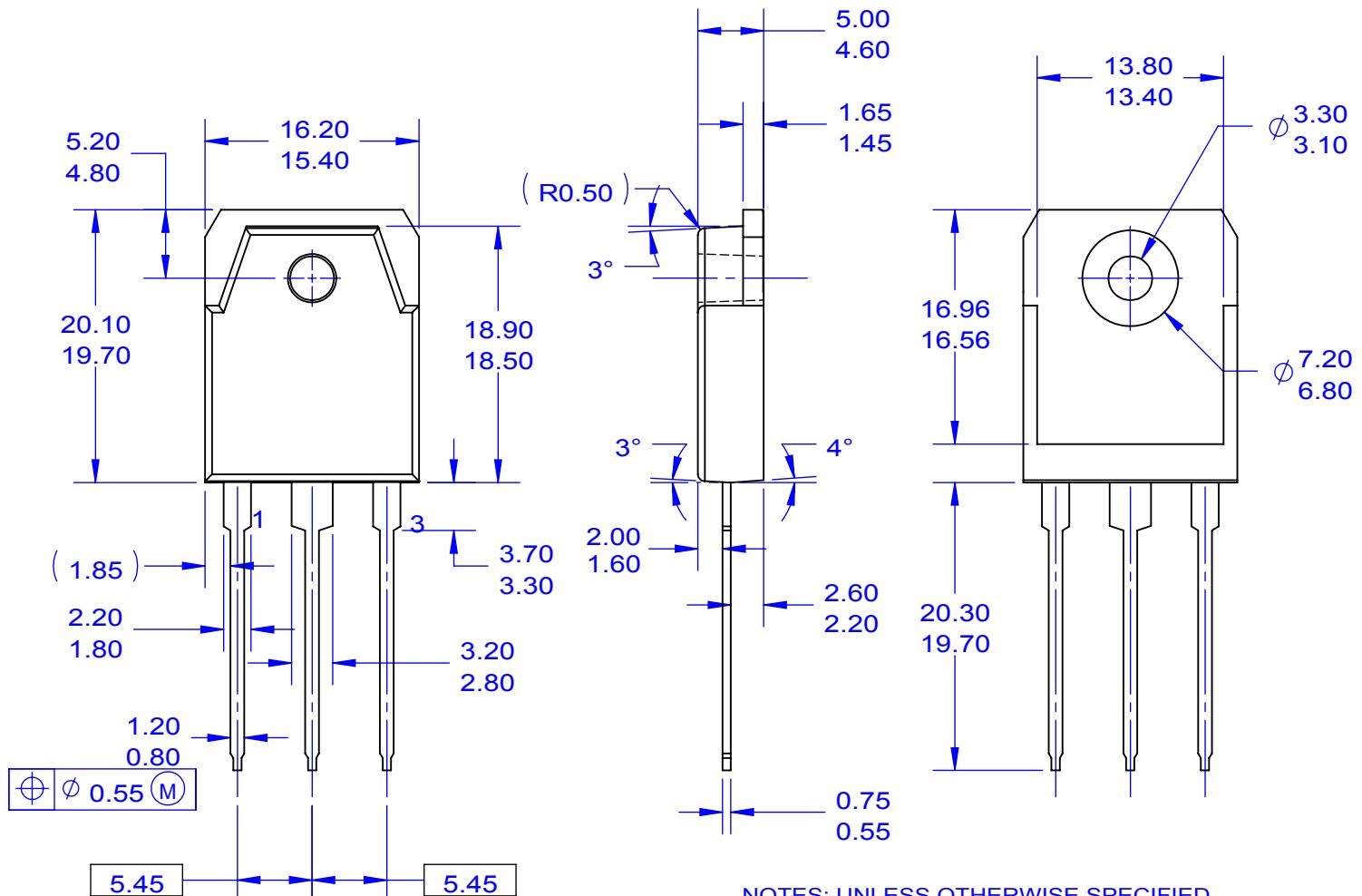


Figure 22. Transient Thermal Impedance of Diode





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No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
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